



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kumar et al.

Serial No.: 09/903,114

U.S. Patent No.: 6,838,115 B2

Issued: January 4, 2005

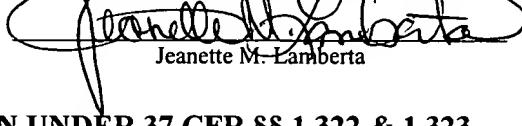
For: THERMAL PROCESSING  
SYSTEM AND METHODS FOR  
FORMING LOW-K DIELECTRIC  
FILMS SUITABLE FOR  
INCORPORATION INTO  
MICROELECTRONIC DEVICES

CERTIFICATE OF  
CORRECTIONS BRANCH

Group Art Unit: 1762 Certificate  
Examiner: B. Talbot FEB 16 2005  
Docket No. FSI0006/US/2 of Correction

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

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Jeanette M. Lamberta

**REQUEST FOR CERTIFICATE OF CORRECTION UNDER 37 CFR §§ 1.322 & 1.323**

Dear Sir or Madam:

It is respectfully requested that the attached Certificate of Correction be issued in connection with the above-identified patent in accordance with the provisions of 37 CFR 1.322 and 1.323.

The errors in Claim 1, column 25, line 21 and Claim 13, column 25, line 66, first occurred in the printed patent and, therefore, were incurred through the fault of the Patent Office. Accordingly, under 37 CFR § 1.322, no fee is due for the correction of these errors.

Applicants first became aware of the typographical errors in claim 7, column 25, line 43; claim 13, column 25, line 67; and claim 23, column 26, line 49 upon proof-reading the patent. Accordingly, under 37 CFR § 1.323, the fee set forth in 37 CFR § 1.20(a), i.e., \$100.00, is enclosed for the correction of these errors.

No other fee is believed to be due in connection with the filing of this Request for Certificate of Correction. However, if any additional fees are found to be required, please charge the fees to deposit Account No. 50-1775 and notify us of the same.

Respectfully Submitted,

  
By:

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Dated: Feb. 4, 2005

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*CGC*  
FEB 17 2005

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO.: 6,838,115 *B2*

DATED: January 4, 2005

INVENTOR(S): Devendra Kumar, Jeffrey D. Womack, Vuong P. Nguyen, Jack S. Kasahara  
and Sokol Ibrani

It is certified that errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Claim 1; column 25, line 21,  
delete "cure" and insert in place thereof --cured--.

Claim 7; column 25, line 43,  
delete "occur" and insert in place thereof --occurs--.

Claim 13; column 25, line 66,  
delete "portion the" and insert in place thereof --portion of the--.

Claim 13; column 25, line 67,  
delete "vaccum" and insert in place thereof --vacuum--.

Claim 23; column 26, line 49,  
delete "vaccum" and insert in place thereof --vacuum--.

MAILING ADDRESS OF SENDER:

PATENT NO. 6,838,115

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THIS WILL ACKNOWLEDGE RECEIPT OF THE FOLLOWING  
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

- REQUEST FOR CERTIFICATE OF CORRECTION UNDER 37 CFR 1.322 & 1.323
- CERTIFICATE OF CORRECTION
- RETURN RECEIPT POSTCARD.

Applicant: Kumar et al.  
Serial No.: 09/903,114  
Filed: July 11, 2001  
U.S. Pat. No. 6,838,115  
Issued: January 4, 2005  
For: THERMAL PROCESSING SYSTEM AND METHODS  
FOR FORMING LOW-K DIELECTRIC FILMS  
SUITABLE FOR INCORPORATION INTO  
MICROELECTRONIC DEVICES  
Docket #: FSI0006/US/2  
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